

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6541043

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SHUJI AIBA	01/06/2021
	HIROYA MUKAIDE	01/08/2021
	KENZO AKIYAMA	01/08/2021
RECEIVING PARTY DATA		
Name:	SODICK CO., LTD.	
Street Address:	3-12-1, NAKAMACHIDAI, TSUZUKI-KU, YOKOHAMA,	
City:	KANAGAWA	
State/Country:	JAPAN	
Postal Code:	224-8522	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	17167101	
CORRESPONDENCE DATA		
Fax Number:	(949)391-4699	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	886223692800	
Email:	usa@jcipgroup.com	
Correspondent Name:	JCIPRNET	
Address Line 1:	8F-1, NO. 100, ROOSEVELT RD. SEC. 2,	
Address Line 4:	TAIPEI, TAIWAN 100404	
ATTORNEY DOCKET NUMBER:	105463-US-933	
NAME OF SUBMITTER:	BELINDA LEE	
SIGNATURE:	/Belinda Lee/	
DATE SIGNED:	02/09/2021	
Total Attachments: 2		
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ASSIGNMENT

WHEREAS,

1. Shuji AIBA
2. Hiroya MUKAIDE
3. Kenzo AKIYAMA

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **INJECTION MOLDING MACHINE AND METHOD FOR INJECTION MOLDING**

[] Filed : Serial No. :

[x] Executed concurrently with the execution of this instrument

WHEREAS, **Sodick Co., Ltd.**
of 3-12-1, Nakamachidai, Tsuzuki-ku, Yokohama, Kanagawa 224-8522, Japan

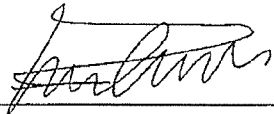
hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

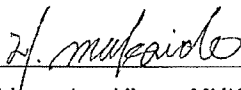
Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: 
Sole or First Joint Inventor: Shuji AIBA

Date: January 6, 2021

Signature: 
Second Joint Inventor: Hiroya MUKAIDE

Date: January 8, 2021

Signature: Kenzo Akiyama
Third Joint Inventor: Kenzo AKIYAMA

Date: January 8, 2021